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FAIRCHILD SEMICONDUCTOR TM

2N5550

Amplifier Transistor

- Collector-Emitter Voltage: V_{CEO}= 140V
- Collector Dissipation: P_C (max)=625mW



TO-92

1. Emitter 2. Base 3. Collector

NPN Epitaxial Silicon Transistor

Absolute Maximum Ratings T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	160	V
V_{CEO}	Collector-Emitter Voltage	140	V
V_{EBO}	Emitter-Base Voltage	6	V
I_C	Collector Current	600	mA
P_C	Collector Dissipation	625	mW
T_J	Junction Temperature	150	°C
T_{STG}	Storage Temperature	-55 ~ 150	°C

• Refer to 2N5551 for graphs

Electrical Characteristics T_a=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
BV_{CBO}	Collector-Base Breakdown Voltage	I_C=100μA, I_E=0	160			V
BV_{CEO}	* Collector-Emitter Breakdown Voltage	I_C=1mA, I_B=0	140			V
BV_{EBO}	Emitter-Base Breakdown Voltage	I_E=10μA, I_C=0	6			V
I_{CBO}	Collector Cut-off Current	V_{CB}=100V, I_E=0			100	nA
I_{EBO}	Emitter Cut-off Current	V_{EB}= 4V, I_C=0			50	nA
h_{FE}	* DC Current Gain	I_C=1mA, V_{CE}=5V I_C=10mA, V_{CE}=5V I_C=50mA, V_{CE}=5V	60 60 20		250	
V_{CE} (sat)	* Collector-Emitter Saturation Voltage	I_C=10mA, I_B=1mA I_C=50mA, I_B=5mA			0.15 0.25	V V
V_{BE} (sat)	* Base-Emitter Saturation Voltage	I_C=10mA, I_B=1mA I_C=50mA, I_B=5mA			1 1.2	V V
f_T	Current Gain Bandwidth Product	I_C=10mA, V_{CE}=10V, f=100MHz	100		300	MHz
C_{ob}	Output Capacitance	V_{CB}=10V, I_E=0, f=1MHz			6	pF
NF	Noise Figure	I_C=250μA, V_{CE}=5V R_S=1KΩ f=10Hz to 15.7KHz			10	dB

* Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

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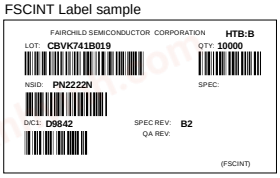
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TO-92 Tape and Reel Data

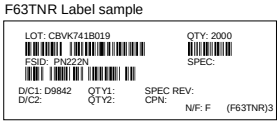
FAIRCHILD SEMICONDUCTOR TM

TO-92 Packaging
Configuration: Figure 1.0

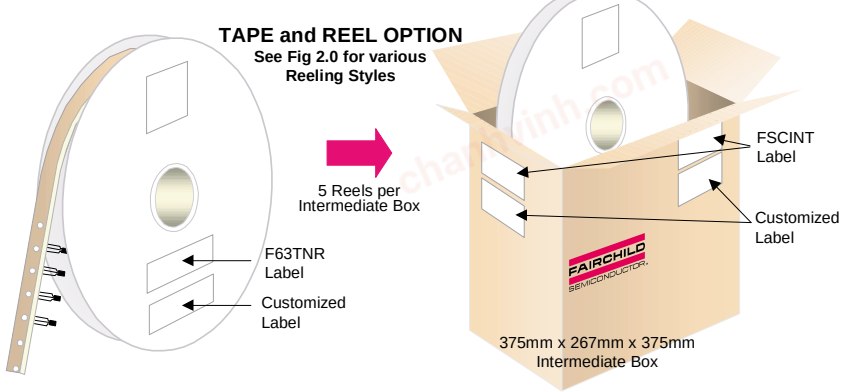
FSCINT Label sample



F63TNR Label sample



TAPE and REEL OPTION
See Fig 2.0 for various Reeling Styles

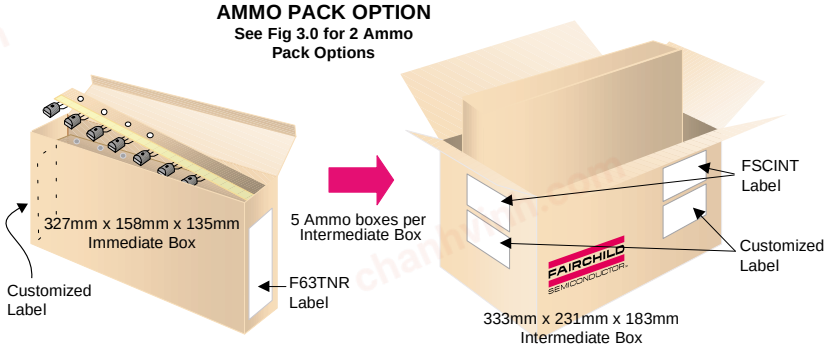


TO-92 TNR/AMMO PACKING INFROMATION

Packing	Style	Quantity	EOL code
Reel	A	2,000	D26Z
	E	2,000	D27Z
Ammo	M	2,000	D74Z
	P	2,000	D75Z

Unit weight = 0.22 gm
Reel weight with components = 1.04 kg
Ammo weight with components = 1.02 kg
Max quantity per intermediate box = 10,000 units

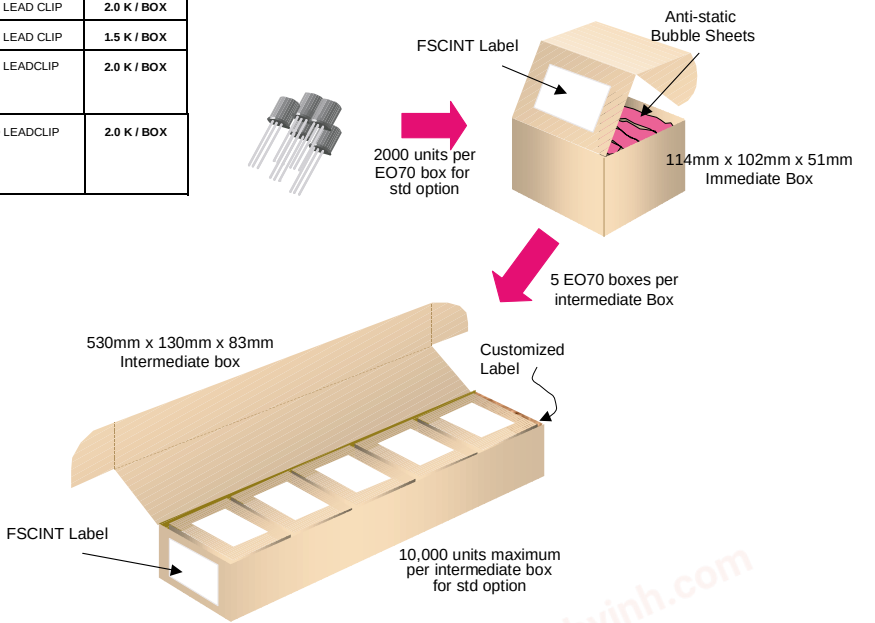
AMMO PACK OPTION
See Fig 3.0 for 2 Ammo Pack Options



(TO-92) BULK PACKING INFORMATION

EOL CODE	DESCRIPTION	LEADCLIP DIMENSION	QUANTITY
J18Z	TO-18 OPTION STD	NO LEAD CLIP	2.0 K / BOX
J05Z	TO-5 OPTION STD	NO LEAD CLIP	1.5 K / BOX
NO EOL CODE	TO-92 STANDARD STRAIGHT FOR: PKG 92, 94 (NON PROELECTRON SERIES), 96	NO LEADCLIP	2.0 K / BOX
L34Z	TO-92 STANDARD STRAIGHT FOR: PKG 94 (PROELECTRON SERIES BCXXX, BFXXX, BSRXXX), 97, 98	NO LEADCLIP	2.0 K / BOX

BULK OPTION
See Bulk Packing Information table



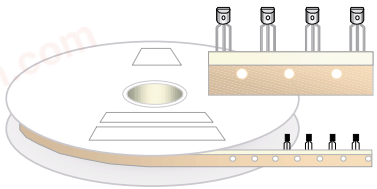
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TO-92 Tape and Reel Data, continued

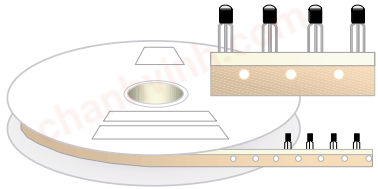
TO-92 Reeling Style
Configuration: Figure 2.0

Machine Option “A” (H)



Style “A”, D26Z, D70Z (s/h)

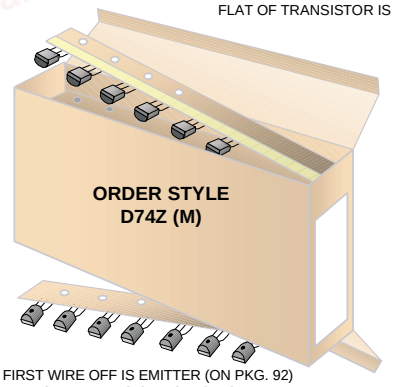
Machine Option “E” (J)



Style “E”, D27Z, D71Z (s/h)

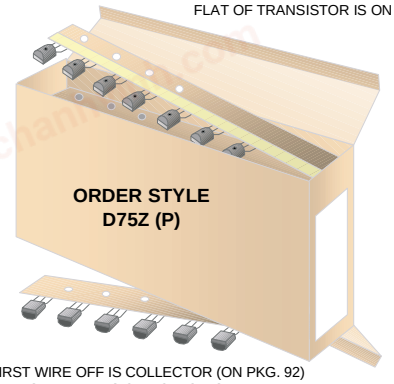
TO-92 Radial Ammo Packaging
Configuration: Figure 3.0

FIRST WIRE OFF IS COLLECTOR
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON TOP



FIRST WIRE OFF IS EMITTER (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

FIRST WIRE OFF IS EMITTER
ADHESIVE TAPE IS ON THE TOP SIDE
FLAT OF TRANSISTOR IS ON BOTTOM

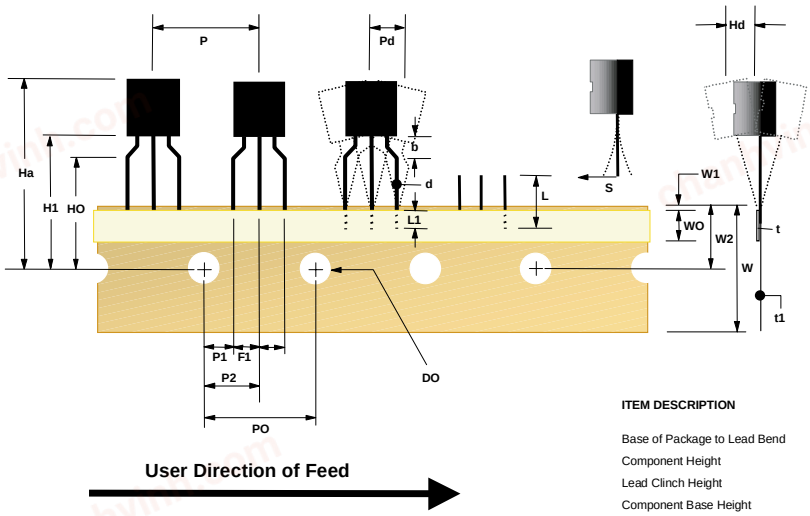


FIRST WIRE OFF IS COLLECTOR (ON PKG. 92)
ADHESIVE TAPE IS ON BOTTOM SIDE
FLAT OF TRANSISTOR IS ON TOP

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TO-92 Tape and Reel Data, continued

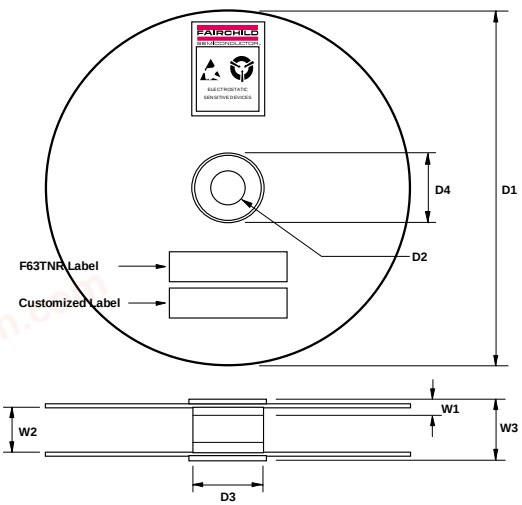
TO-92 Tape and Reel Taping
Dimension Configuration: Figure 4.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	Ha	0.928 (+/- 0.025)
Lead Clinch Height	HO	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0 .010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

Note : All dimensions are in inches.

TO-92 Reel
Configuration: Figure 5.0



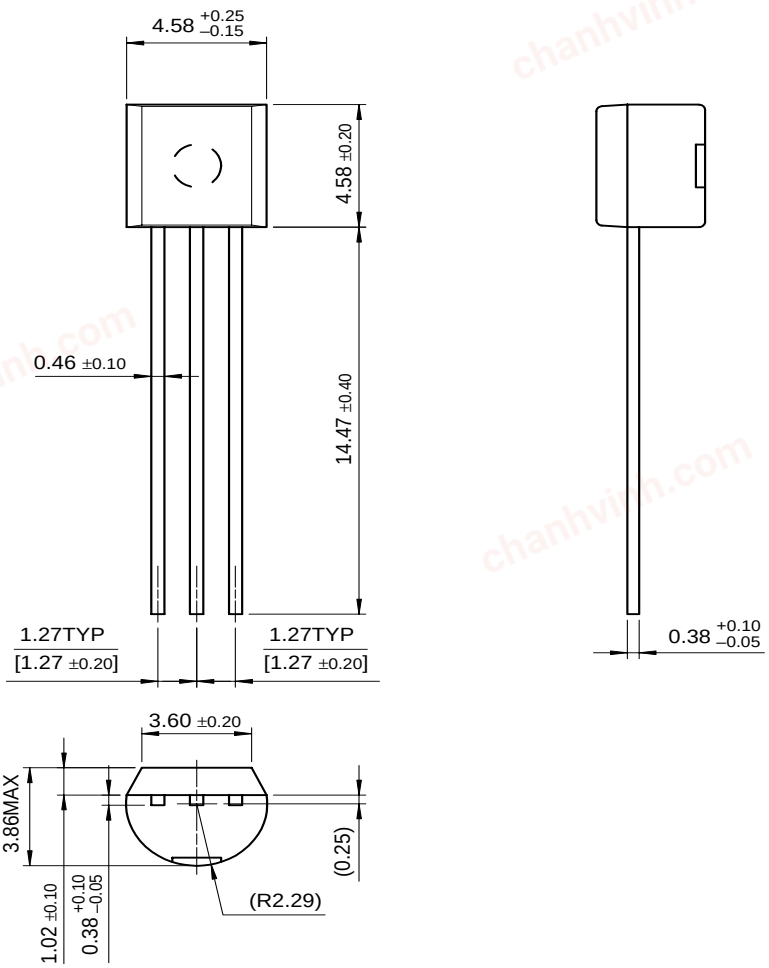
ITEM DESCRIPTION	SYSMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

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Package Demensions

TO-92



Dimensions in Millimeters

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